

GT030D**50V, DC – 6.0GHz, 30W GaN HEMT****FEATURES**

- Operating Frequency Range: DC to 6.0GHz
- Operating Drain Voltage: 28V & 50V
- Maximum Output Power (P_{SAT}): 50W
- Surface Mount Plastic Package
- Suitable for Pulsed, Linear applications
- 100% DC & RF Production Tested



14 Pin 6x3 mm DFN Package

DESCRIPTION

The GT030D is a 50W (P_{3dB}) unmatched discrete GaN-on-SiC HEMT which operates from DC to 6.0GHz on a 50V supply rail. The wide bandwidth of the GT030D makes it suitable for a variety of applications including cellular infrastructure, radar, communications, and test instrumentation, and can support both linear and pulse operations.

The device is housed in an industry-standard 6x3 mm surface mount DFN package. Lead-free and ROHS compliant.

Typical Performances 1 Tone pulsed CW (10% duty cycle, 100 μ s width), 2nd Harmonics NOT optimized

- (1) Optimum Peak Power at 2.5dB in compression
- (2) Optimum Peak Efficiency at 2.5dB in compression

V_{ds}=50V, I_{dq}= 47 mA, T_A = 25°C

Frequency (MHz)	P _{out} ⁽¹⁾ (dBm)	Gain ⁽²⁾ (dB)	Eff ⁽²⁾ (%)
1000	46.2	23.7	65.2
1400	46.6	21.5	67.7
1800	46.7	20.8	64.7
2200	46.8	20.3	61.9
2600	46.9	18.9	66.1
3000	46.9	18.7	64.8
4000	46.9	17	64.5
5000	46.6	14.2	59.7
6000	46.8	13.5	60.8

V_{ds}=28V, I_{dq}= 47 mA, T_A = 25°C

Frequency (MHz)	P _{out} ⁽¹⁾ (dBm)	Gain ⁽²⁾ (dB)	Eff ⁽²⁾ (%)
1000	43.7	20.2	68.9
1400	44.2	19.9	68
1800	44.4	19.4	66.9
2200	44.2	18.7	64
2600	44.4	17.1	68
3000	44.4	16.9	66.7
4000	44.3	14.9	65.7
5000	44	12.8	61.3
6000	44.2	11.3	63.3

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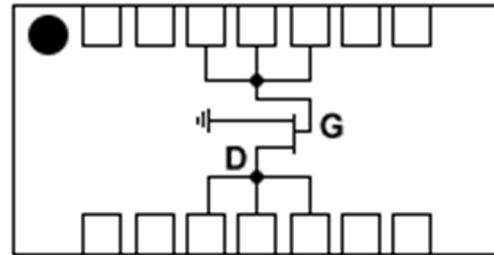
ABSOLUTE MAXIMUM RATINGS^(1, 2)

Parameter	Rating	Symbols and Units
Drain Source Voltage	150	V_{DS} (V)
Gate Source Voltage	-8 to +2	V_{GS} (V)
Operating Voltage	55	V_{dsq} (V)
Junction Temperature	+225	T_{JUNC} (°C)
Storage Temperature	-65 to +150	$T_{STORAGE}$ (°C)
Case Operating Temperature	-40 to +105	T_{CASE} (°C)

1. Exceeding any of these limits may cause permanent damage to this device or seriously limit the life time (MTTF)

2. GalliumSemi does not recommend sustained operation above maximum operating conditions.

BLOCK DIAGRAM

ELECTRICAL SPECIFICATIONS: $T_A = 25^\circ\text{C}$

Parameter	Min.	Typ.	Max.	Symbols and Units	Test conditions
Frequency Range	DC		6000	MHz	
DC Characteristics					
Drain Source Breakdown Voltage	150			V_{BDSS} (V)	
Drain Source Leakage Current		4		I_{DLK} (mA)	$V_{gs} = -8\text{V}$, $V_{ds} = 50\text{V}$
Gate Threshold Voltage	-3.4		-1.5	V_{GS} (V)	$V_{ds} = 50\text{V}$
Operating Conditions					
Gate Bias Voltage		-2.5		V_{GSQ} (V)	
Drain Voltage		50		V_{DSQ} (V)	
Quiescent Drain Current		47		I_{DQ} (mA)	

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RF ELECTRICAL SPECIFICATIONS: $T_A = 25^\circ\text{C}$, $V_{DS} = 50\text{ V}$, $I_{DQ} = 47\text{ mA}$, Freq= 3600MHz
Note: Performance⁽¹⁾ in GalliumSemi Production Test Fixture, 50 Ω system

Parameter	Symbol	Min.	Typ.	Max.	Units	Notes
Small Signal Gain	G_{ss}		15.1		dB	
Power Gain	G_{SAT}		15.2		dB	
Saturated Drain Efficiency	$DEff_{SAT}$		58.1		%	
Saturated Output Power	P_{SAT}		47		dBm	
Ruggedness Output mismatch	Ψ	VSWR = 10:1, all angles				No damage or shift in performances

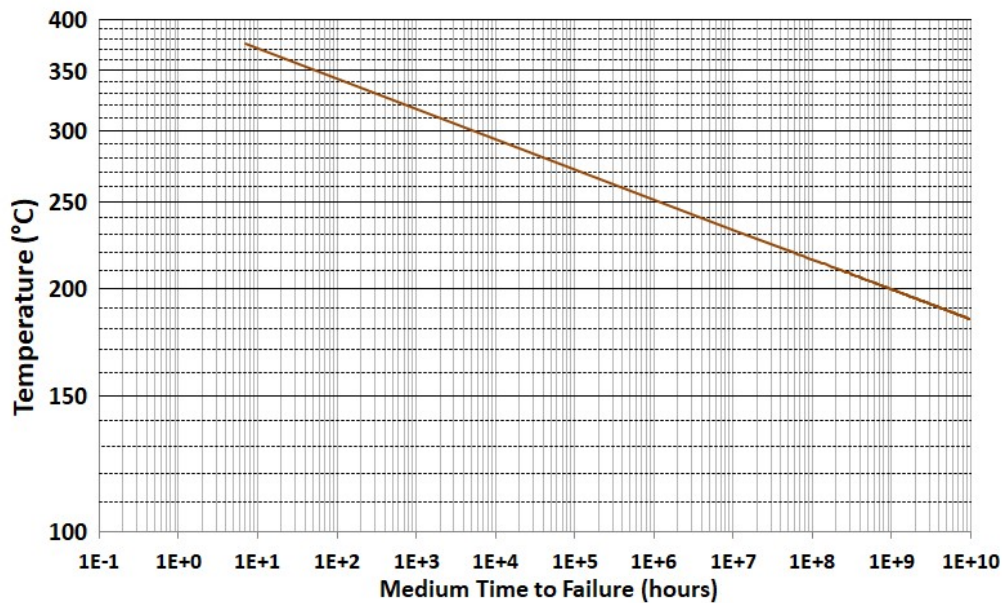
1. 1 Tone Pulse CW, pulse width 100us, duty cycle 10%

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THERMAL AND RELIABILITY INFORMATION -CW ^(1, 2): T_c = 85°C

Parameter	Test condition	Value	Units	Notes
Channel Temperature, T _{ch}		126.6	°C	
R _{th}	P _{diss} 9 W	4.62	°C/W	
MTTF		>1.0E+10	Hrs	
Channel Temperature, T _{ch}		173.4	°C	
R _{th}	P _{diss} 18 W	4.91	°C/W	
MTTF		1.0E+10	Hrs	
Channel Temperature, T _{ch}		232	°C	
R _{th}	P _{diss} 28 W	5.25	°C/W	
MTTF		1.0E+07	Hrs	

1. Assumes eutectic attach using 1mil low temp solder.t
2. Thermal Resistance using Finite Element Analysis (FEA) simulation, calibrated with Infrared measurement on surface temperature.



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LOADPULL MEASUREMENT, $V_{ds} = 50V$ $I_{dq} = 47$ mA

1 Tone Pulse CW, pulse width 100us, duty cycle 10%

For Optimum Peak Power @ 2.5dB Compression

Freq-MHz	Zin_F0	ZI_F0	Gain-dB	Pout-dBm	Pout-W	Eff-%	AMPM-deg
1000	4.2 j -13.2	21.1 j 4.4	22.6	46.2	42.3	58.4	1
1200	3.0 j -11.0	17.4 j 7.7	22.3	46.5	45.4	60.4	1.8
1400	2.5 j -8.7	16.3 j 7.9	21.7	46.6	46.2	60.2	2
1600	2.5 j -7.3	12.8 j 4.8	19.5	47	50.2	54.5	3.2
1800	1.9 j -5.5	15.2 j 5.8	19.9	46.7	47.2	55.6	2.3
2000	2.3 j -4.6	14.0 j 4.1	18.9	46.6	45.6	50.8	2.2
2200	1.8 j -3.3	13.9 j 4.6	18.1	46.8	47.6	53.1	2.7
2400	1.6 j -2.1	12.5 j 7.1	18	46.7	46.4	56.6	3.1
2800	1.7 j -0.3	11.5 j 5.2	17.7	47	50.6	57	1.1
3000	1.7 j 0.6	11.6 j 3.0	16.8	46.9	49	53.1	0.8
3500	1.8 j 2.6	9.3 j 1.4	15.5	46.8	48.1	50.2	-0.2
4000	1.7 j 4.7	7.9 j 1.1	15.3	46.9	48.7	53.7	-1.3
4500	1.7 j 6.5	7.7 j -1.0	13.4	46.7	47.5	48.6	-1.9
5000	1.8 j 9.1	7.0 j -0.5	13.7	46.6	46.2	54.5	-1.9
5500	2.0 j 10.5	6.1 j -2.5	12.7	46.7	47	54.9	-1.8
6000	2.5 j 14.3	7.2 j -5.0	11.8	46.8	48.4	52.5	-1.1

For Optimum Peak Efficiency @ 2.5dB Compression

Freq-MHz	Zin_F0	ZI_F0	Gain-dB	Pout-dBm	Pout-W	Eff-%	AMPM-deg
1000	2.6 j -11.5	24.9 j 13.0	23.7	45.9	38.9	65.2	-0.9
1200	2.5 j -9.8	20.9 j 14.0	23.1	46.1	40.7	65.8	0.5
1400	2.2 j -7.4	22.8 j 18.4	21.5	45.7	37.7	67.7	3.4
1600	2.1 j -5.1	17.5 j 19.1	21.1	45.4	34.9	68.3	-0.6
1800	1.7 j -4.3	15.9 j 14.7	20.8	46.1	41.4	64.7	2.2
2000	2.1 j -3.5	18.0 j 16.4	19.4	45.9	38.7	61.9	4.2
2200	1.4 j -2.4	12.9 j 12.4	20.3	46.2	41.3	61.9	1.6
2400	1.2 j -1.1	10.6 j 14.0	19.7	45.6	36.2	61.2	1.6
2800	1.3 j 0.6	9.1 j 13.5	18.4	45.7	37.4	65.1	1.5
3000	1.1 j 1.8	8.9 j 12.4	18.7	45.5	35.6	64.8	0.2
3500	1.1 j 3.7	5.8 j 7.2	17.6	45.8	38.7	63.4	-1.2
4000	1.0 j 5.7	4.9 j 5.9	17	45.5	35.5	64.5	-2.1
4500	1.3 j 7.3	4.4 j 3.6	15.4	45.7	37.3	61.8	-1.9
5000	1.3 j 9.6	4.7 j 1.1	14.2	45.9	39.4	59.7	-2.7
5500	1.5 j 11.3	3.0 j -0.3	13.9	44.8	30.2	60.7	-2.7
6000	1.8 j 15.1	3.5 j -2.2	13.5	45.4	34.9	60.8	-0.9

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LOADPULL MEASUREMENT, Vds= 28V Idq = 47 mA

1 Tone Pulse CW, pulse width 100us, duty cycle 10%

For Optimum Peak Power @ 2.5dB Compression

Freq-MHz	Zin_F0	ZI_F0	Gain-dB	Pout-dBm	Pout-W	Eff-%	AMPM-deg
1000	4.6 j -13.3	12.2 j -2.2	20.6	43.7	23.3	55.2	0.4
1200	3.7 j -11.0	12.3 j -1.0	19.7	43.9	24.8	57.1	1.4
1400	2.9 j -8.8	11.5 j 0.8	18.8	44.2	26.5	60.7	3.5
1600	2.9 j -7.1	10.4 j -0.8	18	44.4	27.4	56.1	0.6
1800	2.3 j -5.5	11.0 j 0.2	18.3	44.4	27.3	57.7	1.1
2000	2.1 j -4.3	11.5 j 0.7	17.8	44.1	25.8	56	1.6
2200	2.0 j -3.2	10.8 j -0.7	17	44.2	26.5	54.9	1.1
2400	1.8 j -2.1	10.7 j 0.3	16.8	44.2	26.1	56.1	0.7
2800	1.4 j 0.0	9.9 j 0.7	16.2	44.4	27.7	60.1	0.2
3000	1.5 j 0.9	9.4 j 0.3	16.4	44.4	27.5	60.4	-1.3
3500	1.6 j 2.9	7.9 j -1.0	15	44.4	27.2	58.1	-1.9
4000	1.4 j 5.1	7.1 j -1.3	14.5	44.3	26.8	60.9	-2.9
4500	1.9 j 6.7	8.2 j -3.9	12.4	44.2	26.1	53.6	-2.3
5000	1.4 j 9.5	5.9 j -4.7	12	44	25.4	57.2	-3.4
5500	1.8 j 10.9	6.6 j -6.1	10.9	44	25.9	57.3	-2.7
6000	2.2 j 14.8	7.9 j -7.1	10.6	44.2	26.5	58	-1.3

For Optimum Peak Efficiency @ 2.5dB Compression

Freq-MHz	Zin_F0	ZI_F0	Gain-dB	Pout-dBm	Pout-W	Eff-%	AMPM-deg
1000	3.5 j -11.7	20.0 j 1.7	20.2	43	20.4	68.9	0.1
1200	2.5 j -8.5	20.1 j 7.6	20.4	42.6	18.5	67.6	2.4
1400	2.3 j -7.5	19.3 j 8.4	19.9	42.8	19.2	68	3.1
1600	2.3 j -4.8	17.9 j 10.4	18.4	42.5	17.9	68.6	0
1800	1.5 j -3.9	13.7 j 8.0	19.4	43.2	21.1	66.9	0.7
2000	1.7 j -3.4	15.2 j 7.7	18	43.3	21.6	62.8	3
2200	1.1 j -1.8	10.6 j 7.6	18.7	43.2	20.7	64	0.1
2400	1.4 j -1.3	11.0 j 8.7	17.5	42.8	19	62.7	0.9
2800	1.1 j 1.2	9.3 j 8.1	16.8	42.9	19.6	67	-0.5
3000	1.0 j 2.1	8.7 j 7.1	16.9	42.7	18.8	66.7	-1.5
3500	1.1 j 3.5	6.6 j 2.5	15.3	43.7	23.9	66.2	-3
4000	1.1 j 5.8	6.1 j 1.9	14.9	43.2	21	65.7	-3.4
4500	1.3 j 7.7	4.6 j 0.5	13.6	42.8	19	64	-5
5000	1.3 j 9.8	5.1 j -1.8	12.8	43	19.9	61.3	-4.3
5500	1.4 j 11.5	3.7 j -4.1	11.6	42.8	19.5	63.1	-7.3
6000	1.7 j 15.4	4.2 j -6.0	11.3	43.2	21	63.3	-4.9

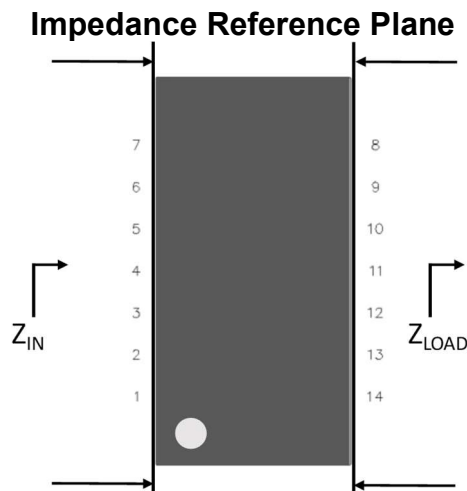
LOADPULL MEASUREMENT NOTES

Source and Load impedance @ 2nd Harmonic are set to 10 Ohms

With proper 2nd Harmonic termination, expect +5% Efficiency for Source and similar with Drain 2nd Harmonic.

Z_{LOAD} : Measured Impedance presented to the output of the device in the reference plane

Z_{IN} : Measured input Impedance at the input of the device in the reference plane

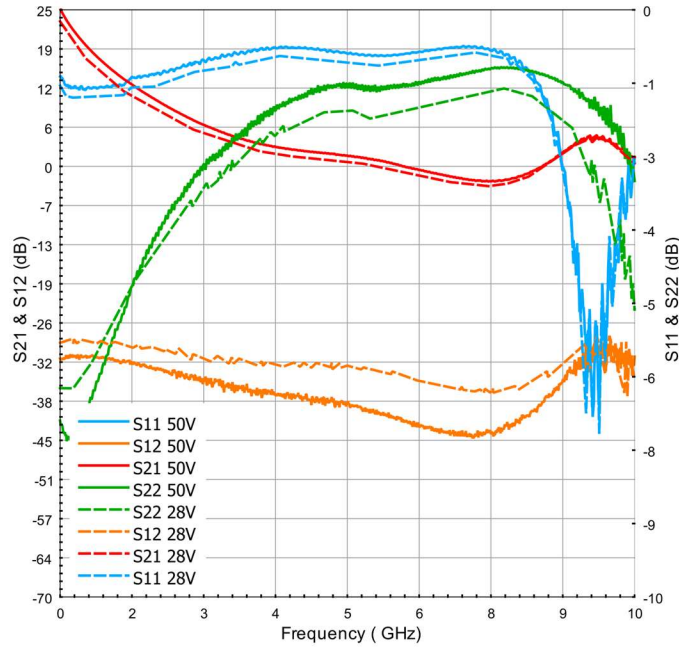


Raw data and full Loadpull measurement report available at request: sales@galliumsemi.com

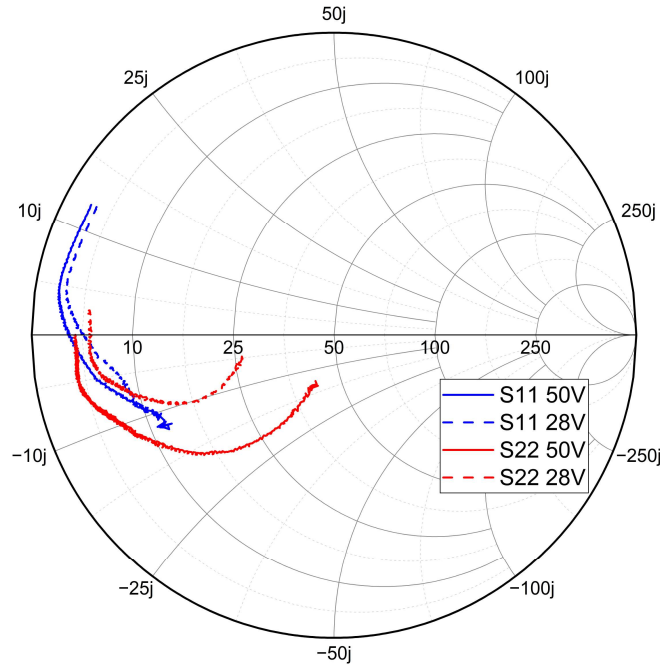
GT030D **50V, DC – 6.0GHz, 30W GaN HEMT**

BROADBAND S-PARAMETERS MEASUREMENT, $V_{ds}= 28 \text{ \& 50V}$ $I_{dq} = 47 \text{ mA}$
1 Tone CW

S Parameters (Mag-dB)



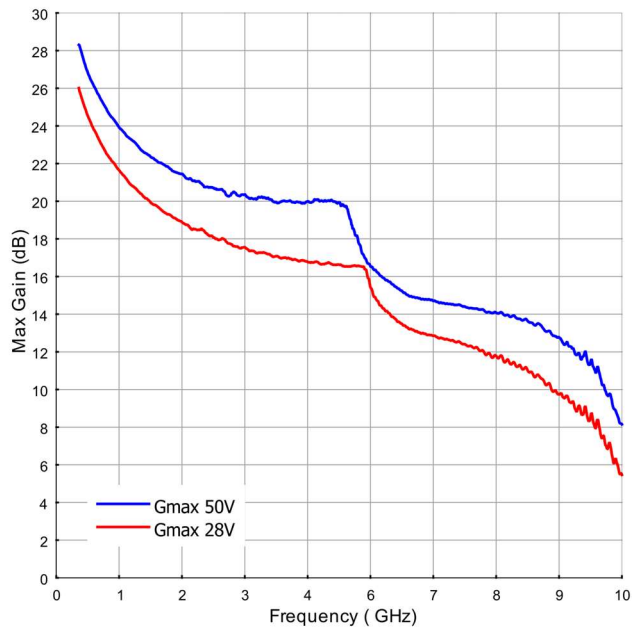
S11 & S22 0.4-6 GHz



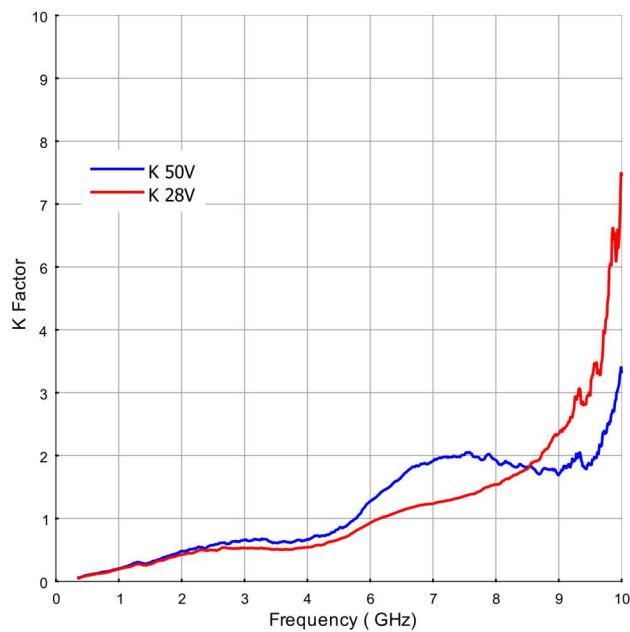
GT030D **50V, DC – 6.0GHz, 30W GaN HEMT**

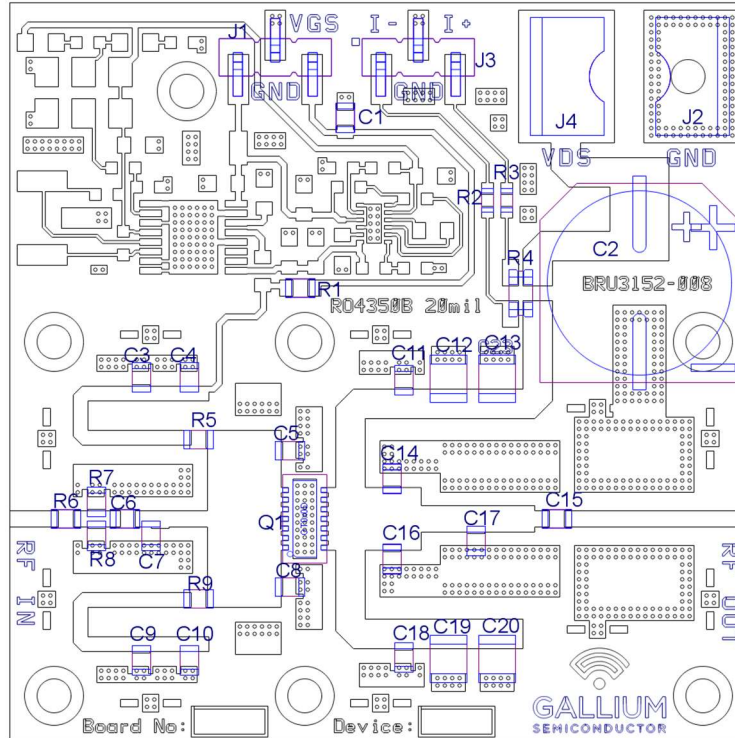
BROADBAND S-PARAMETERS MEASUREMENT, $V_{ds} = 28$ & $50V$ $I_{dq} = 47$ mA
1 Tone CW

Maximum Available Gain



K Factor



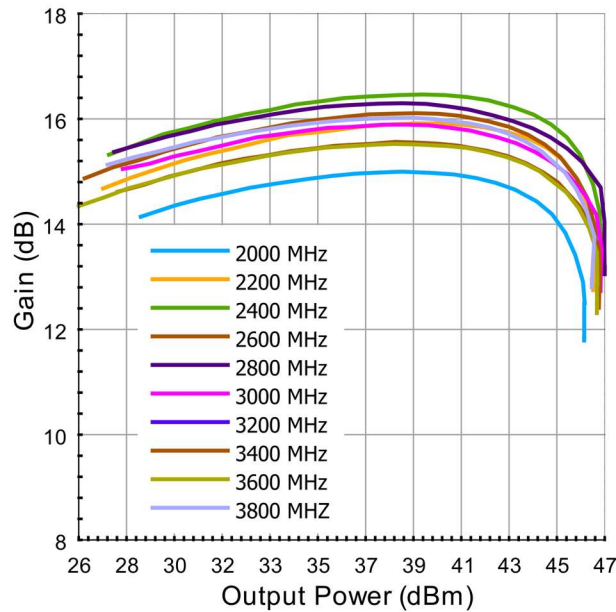
GT030D**50V, DC – 6.0GHz, 30W GaN HEMT****EVALUATION TEST FIXTURE 2.1-3.7 GHz**

COMPONENT DESIGNATOR	VALUE	SIZE	PART NUMBER	REMARKS
Q1	GT030D	6 x 3 mm DFN	Gallium GT030D	
C1	10 μ F	0805	Murata GRM21BC71E106K	-
C2	220 μ F	12.5 mm	Nichicon UCZ1J221MN1Z	63 V
C3 C9, C11, C15, C18	6.8 pF	0805	ATC 600F6R8BT250XT	ATC 600F series
C4, C10	10 nF	0805	Murata GRM2165C2A103J	-
C5, C8	0.7 pF	0805	ATC 600F0R7AT250XT	ATC 600F series
C6	3.3 pF	0805	ATC 600F3R3BT250XT	ATC 600F series
C7	1.1 pF	0805	ATC 600F0R7AT250XT	ATC 600F series
C12, C13, C19, C20	10 μ F	1210	Murata GRM32EC72A106K	100V
C14, C16	0.6 pF	0805	ATC 600F0R6AT250XT	ATC 600F series
C17	0.8 pF	0805	ATC 600F0R8AT250XT	ATC 600F series
J1	Pin header	5.1 mm	Samtec TSM-103-01-L-SV	Gate circuit supply
J3	Pin header	5.1 mm	Samtec TSM-103-01-L-SV	Current sense resistor outputs
J4	Faston connector	6.3 x 0.8 mm	-	Drain supply
J5	Faston connector	6.3 x 0.8 mm	-	Drain supply ground reference
PCB	PCB	50.0 x 50.0 mm	-	Rogers RO4350B, 20 mill thickness
R1	DNP	0805	-	0 Ω
R2, R3	1.0 k Ω	0603	-	-
R4	10 m Ω	1206	Ohmite LVK12R010C	0.5 W, 0.25 %
R5	5.1 Ω	0805	Yageo RT0805DRD075R1L	-
R6	2.0 Ω	0805	Vishay PCAN0805K2R00F	1 W, 1 %
R7, R8	1.0 k Ω	0805	Vishay PCAN0805E1001B	1 W, 0.1 %
R9	DNP	0805	-	-

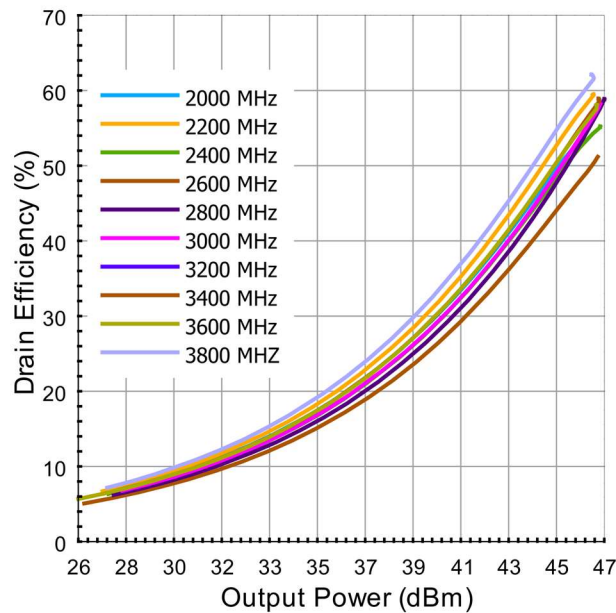
GT030D **50V, DC – 6.0GHz, 30W GaN HEMT**

Typical Performance Curves as Measured in the 2.1-3.7 GHz Evaluation Test Fixture:
 Pulsed CW (10% duty cycle, 100µs width) , VDS = 50 V, IDQ =47 mA, TC = 25°C (Unless Otherwise Noted)

Gain vs. Output Power and Frequency



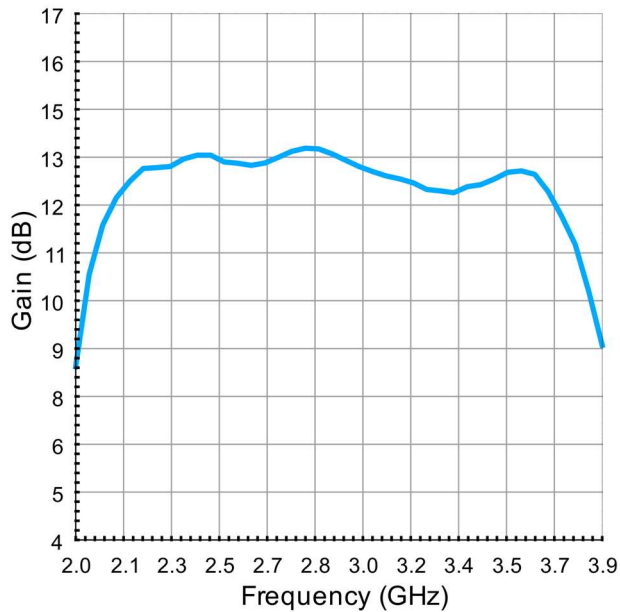
Drain Efficiency vs. Output Power and Frequency



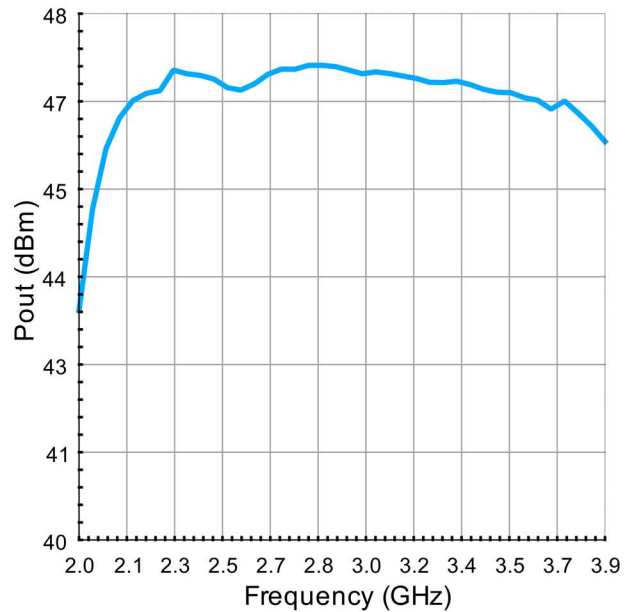
GT030D 50V, DC – 6.0GHz, 30W GaN HEMT

Typical Performance Curves as Measured in the 2.1-3.7 GHz Evaluation Test Fixture:
 Pulsed CW (10% duty cycle, 100µs width) , VDS = 50 V, IDQ =47 mA, TC = 25°C (Unless Otherwise Noted)

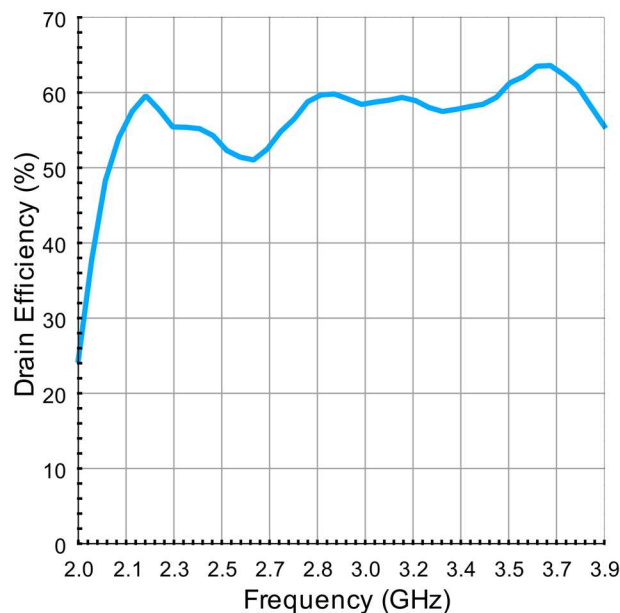
Gain vs. Frequency, 2.5dB Compression



Pout vs. Frequency, 2.5dB Compression



Drain Efficiency vs. Frequency, 2.5dB Compression



GT030D

50V, DC – 6.0GHz, 30W GaN HEMT

GaN HEMT BIASING SEQUENCE

To turn the transistor ON

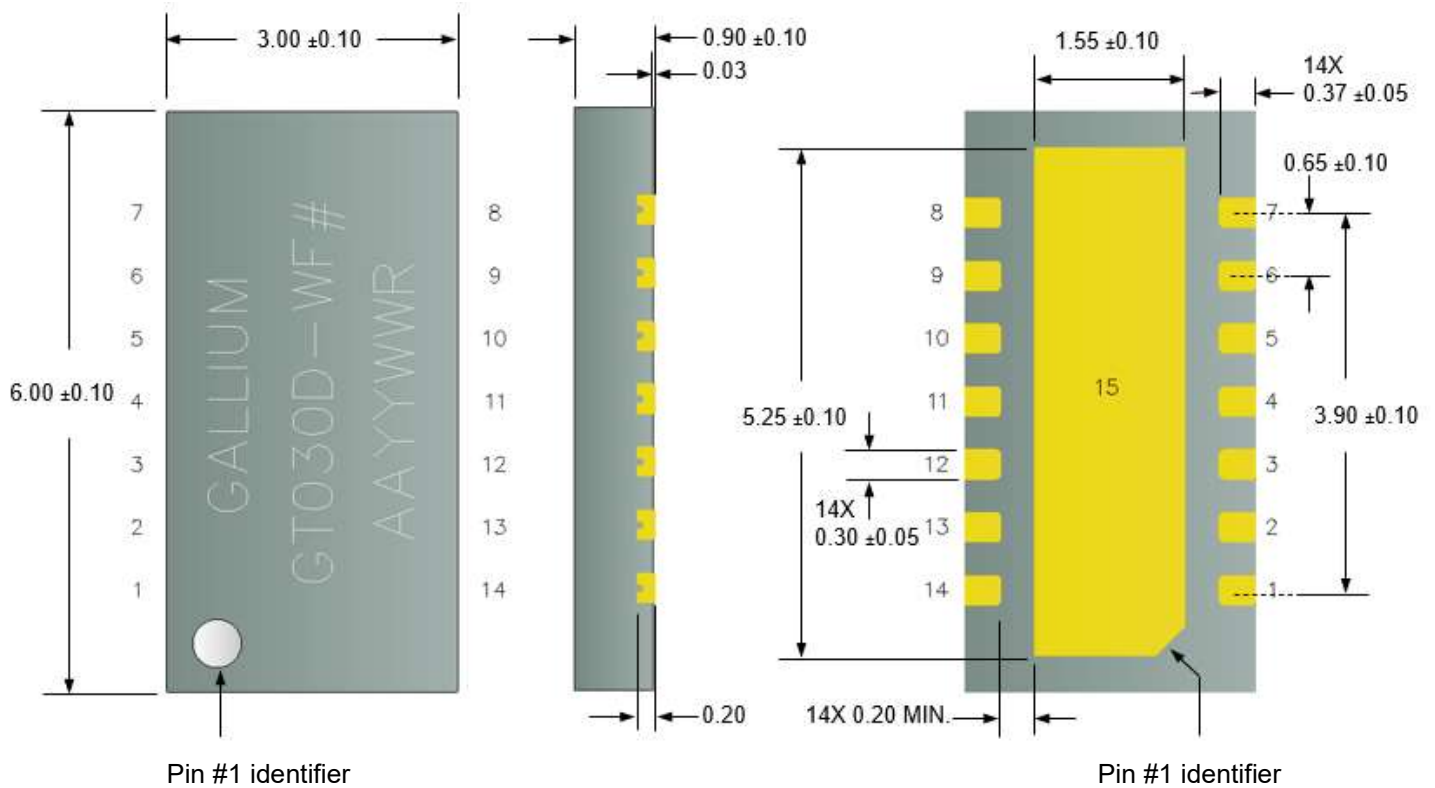
1. Set V_{GS} to -5V
2. Turn on V_{DS} to normal operation voltage (50V)
3. Slowly increase V_{GS} to set I_{DQ} current (47mA)
4. Apply RF power

To turn the transistor OFF

1. Turn the RF power off
2. Decrease V_{GS} to -5V
3. Turn off V_D . Wait a few seconds for drain capacitor to discharge
4. Turn off V_{GS}

GT030D **50V, DC – 6.0GHz, 30W GaN HEMT**

PACKAGE DIMENSIONS



Note: Dimension in mm

PIN CONFIGURATION

Pin	Input/Output
1, 2	Not connected
3, 4, 5	RF Input / Gate Voltage
6, 7, 8, 9	Not connected
10, 11, 12	RF Output / Drain Voltage
13, 14	Not connected
15 (Paddle)	Ground

DEVICE LABEL

Line 1:	COMPANY NAME: GALLIUM
Line 2:	PART NUMBER - WAFER #
Line 3:	AA: Assembly Code
	YYWW: Assembly Date Code
	R: Reserved code

GT030D**50V, DC – 6.0GHz, 30W GaN HEMT****HANDLING PRECAUTIONS**

Parameter	Symbol	Class	Test Methodology
ESD – Human Body Model	HBM	Class 1A (250 V)	ANSI/ESDA/JEDEC Standard JS-001
ESD – Charged Device Model	CDM	Class C3 (1500 V)	ANSI/ESDA/JEDEC Standard JS-002
MSL – Moisture Sensitivity Level	MSL	MSL 1	IPC/JEDEC Standard J-STD-020

**RoHS COMPLIANCE**

Gallium Semiconductor's Policy on EU RoHS available online:

https://www.galliumsemi.com/files/ugd/3748d3_1107b9788f9845f78f45d424097c4c97.pdf

GT030D

50V, DC – 6.0GHz, 30W GaN HEMT

CONTACT INFORMATION

To request latest information and samples, please contact us at:

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